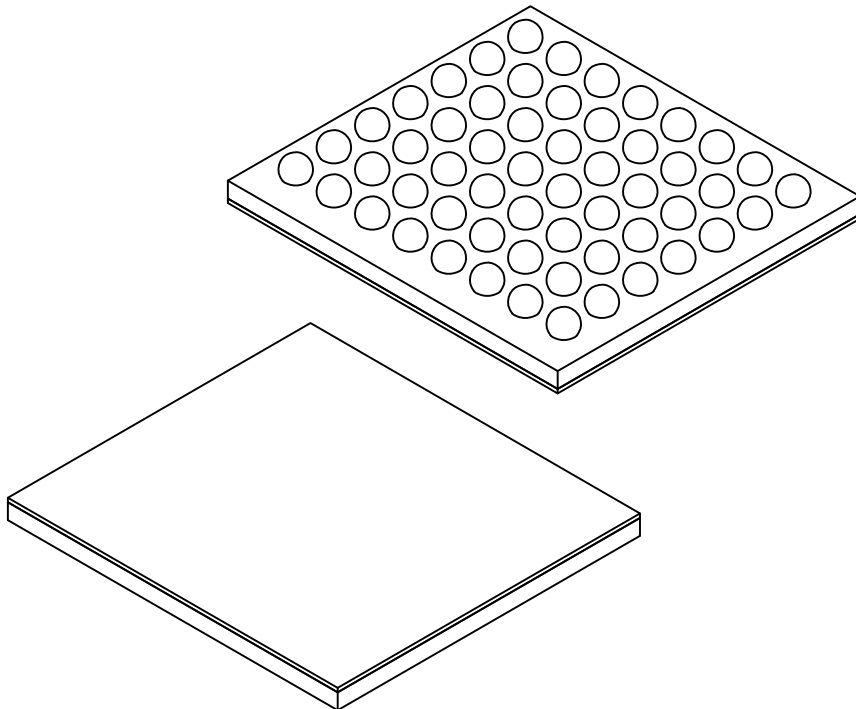


56-ball Wafer Level Chip Scale Package (FZB) - 3.170x3.444x0.483 mm Body [WLCSP] Atmel Legacy GPC GBL

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		56		
Pitch	eD		0.40 BSC		
Pitch	eE		0.40 BSC		
Overall Height	A	0.403	0.443	0.483	
Ball Height	A1	0.17	-	0.23	
Wafer Thickness	A2	0.178	0.203	0.228	
Backside Coat Thickness	A3		0.040 REF		
Overall Length	D		3.170 BSC		
Ball Array Length	D1		2.400 BSC		
Overall Width	E		3.444 BSC		
Ball Array Width	E1		2.800 BSC		
Ball Width	b	0.23	0.26	0.29	
Ball Diameter			0.25 REF		

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.